

Product Disassembly Instructions

Product Category:

Panel PC

Product Marketing Name / Model:

PPC-3060S

Purpose: The document provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC and 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.



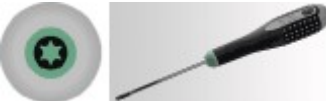
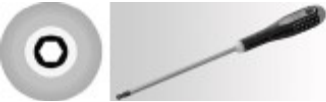




Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq. cm Mother board, Card Reader board, USB Daughter board, LID Daughter board	5
Batteries	All types including standard alkaline and lithium coin or button style batteries 6cell battery or 9 cell battery, and RTC battery	1
External electrical cables and Power cord		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Gas Discharge Lamps		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0

Item Description	Notes	Quantity of items included in product
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Capacitors / condensers (Containing		0

PCB)		
Plastics containing Brominated Flame Retardants weighing > 25 grams	(Not including PCBs or PCAs already listed as a separate item above)	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Asbestos waste and components which contain asbestos		0
Components containing refractory ceramic fibers		0
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons(HFC), hydrocarbons (HC)		0
Components, parts and materials containing radioactive substances		0

Disassembly Tool

List the tools that would typically be used to disassemble the product to a point where components and materials can be removed.

Disassembly Tool	Picture
Screwdriver	
Lever	
Star Screwdriver	
Hexagon Driver	
Slanted pliers	
Pliers	
Hammer	
Knife	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials.

A. Disassembly Box module.

- A-1. Disassembly 1 pcs screw to remove the mSATA door.
- A-2. Disassembly 4pcs screw and 4pcs Hex from COM port to remove the Rear cover.
- A-3. Disassembly 4 pcs screw from mother board to separate the Mother board & Battery chassis.
- A-4. Disassembly DDR module from DDR socket.
- A-5. Disassembly 4pcs screw to remove Heatsink module.
- A-6. Disassembly Mini PCIe card(2pcs screw) from socket.
- A-7. Disassembly mSATA card(2pcs screw) from socket.
- A-8. Remove RTC battery wire cable.

B. Disassembly Panel module.

- B-1. Disassembly screw 3pcs to remove the LCD module.
- B-2. Disassembly screw 4pcs to separate the LCD and main board frame.
- B-3. Separate the LCD sponge from LCD opening bezel.
- B-5. Remove the waterproof from front bezel.

3.2 Exploded view drawing. Insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

